



Application No.: 10/049,499

Attorney Docket No.: FUK-89

Amendment Dated: October 5, 2005

Reply for Office Action Dated: 12 April 2005

AMENDMENTS TO THE CLAIMS

1. (CURRENTLY AMENDED) A method of producing a multilayered printed-circuit board, comprising the steps of:

stacking up in spaced-apart relationship at least one outer layer, at least one inner layer, and at least one prepreg to form a stacked formation, the at least one outer layer including a

5 laminated sheet covered with conductive foil or conductor ~~for an outer layer, a prepreg and the at~~
least one inner layer including a laminated sheet covered with conductor for an inner layer;

thereafter,

laminating the stacked formation to provide a lamination and then setting the prepreg by
pressurizing/heating the lamination; and

10 before conducting the laminating and the pressurizing/heating operations, flowing a gas
over and into contact with the surfaces of the stacked formation ~~gas is sprayed on the surfaces of~~
~~the laminated sheet covered with conductive foil or conductor for the outer layer, a prepreg and a~~
~~laminated sheet covered with conductor for the inner layer~~ to eliminate impurities from the
surfaces.

2. (PREVIOUSLY PRESENTED) The method according to claim 1, wherein said gas is
a dried gas.

3. (PREVIOUSLY PRESENTED) The method according to claim 2, wherein said dry
gas is a heated gas.

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4. (CURRENTLY AMENDED) A method of producing a multilayered printed-circuit board, comprising the steps of:

preparing a plurality of wiring boards having a circuit formed with conductive foil, and having through holes filled with a through hole ~~conduct~~ conductor; [[or]]

5 disposing the wiring boards in stacked spaced-apart relationship to one another to form a stacked formation;

multilayering by laminating the stacked formation to provide a lamination and then
pressurizing/heating the lamination ~~plurality of wiring boards each other, and sprayed gas on a~~
~~surface of the wiring board to eliminate impurities from the wiring board surface before~~
10 ~~pressurizing/heating~~[[.]]; and

prior to conducting the laminating and pressurizing/heating operations, flowing a gas
over and into contact with the surfaces of the wiring boards in the stacked formation to eliminate
impurities from the wiring board surfaces.

5. (CURRENTLY AMENDED) The method according to claim 1, wherein the pressure during said pressurizing step is between 10 to 15 ~~kg/cm²~~ kgf/cm².

6. (CANCELLED)

7. (CANCELLED)

8. (NEW) A method of producing a multilayered printed-circuit board, comprising the steps of:

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providing a plurality of layers in stacked spaced-apart relationship to one another to
define a stacked formation;

5 laminating the stacked formation to provide a lamination; and

prior to the laminating operation, flowing a gas over and into contact with the surfaces of
the stacked formation to remove impurities from the surfaces.

9. (NEW) The method as recited in Claim 8, further includes the step of:

pressurizing/heating the lamination.

10. (NEW) The method as recited in Claim 8, wherein the plurality of layers further
includes at least one outer layer, at least one inner layer, and at least one prepreg, the at least one
outer layer including a laminated sheet covered with conductive foil or conductor, the at least
one inner layer including a laminated sheet covered with conductor.

11. (NEW) The method as recited in Claim 10, further includes the step of:

pressurizing/heating the lamination to set the prepreg.

12. (NEW) The method as recited in Claim 8, wherein the plurality of layers further
includes a plurality of wiring boards.

13. (NEW) The method as recited in Claim 12, further includes the step of:

pressurizing/heating the lamination.